

ABSTRACT OF THE DISCLOSURE

SLURRY USED IN POLISHING A SUBSTRATE

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An object is to provide a carrier plate that can suppress the increase of a difference in polishing (grinding) depth between upper and lower surfaces of a polished (ground) disc-shaped substrate.

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This carrier plate is a carrier plate that is provided in a double-sided machining device polishing or grinding both upper and lower surfaces of disc-shaped substrates, and includes substrate holding holes that hold the disc-shaped substrates and strip-shaped blades that are formed on at least one surface of the carrier plate so as to protrude.

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FIG. 2